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Part Number: [0783150011](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, Very Low Profile, Vertical, Press-Fit, with Pegs, Black Housing and Latches, 0.76µm (30µ") Gold (Au)Plating, 2.85mm (.112") Compliant Pin Length, 2.60mm (.102") PCB Thickness, 240 Circuits, Lead free

Documents:

[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-78315-001 \(PDF\)](#)

General

Product Family	Memory Module Sockets
Series	78315
Component Type	Socket
JEDEC Outline	MO-269
Product Name	DDR3 DIMM

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black
Durability (mating cycles max)	25
Entry Angle	Vertical
Function Key	None
Keying to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
PC Tail Length (in)	0.112 In
PC Tail Length (mm)	2.85 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.102 In
PCB Thickness Recommended (mm)	2.60 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Pitch - Term. Interface (in)	0.039 In
Pitch - Term. Interface (mm)	1.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.38
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	30V AC (RMS)/DC
Voltage Key	Center

Material Info

Reference - Drawing Numbers

Application Specification	AS-78315-001
Product Specification	PS-78315-001, RPS-78315-001

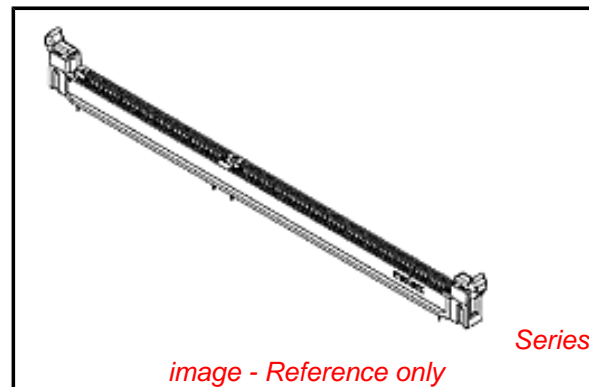


image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
**REACH SVHC
Contains SVHC: No**
**Halogen-Free
Status
Not Reviewed**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

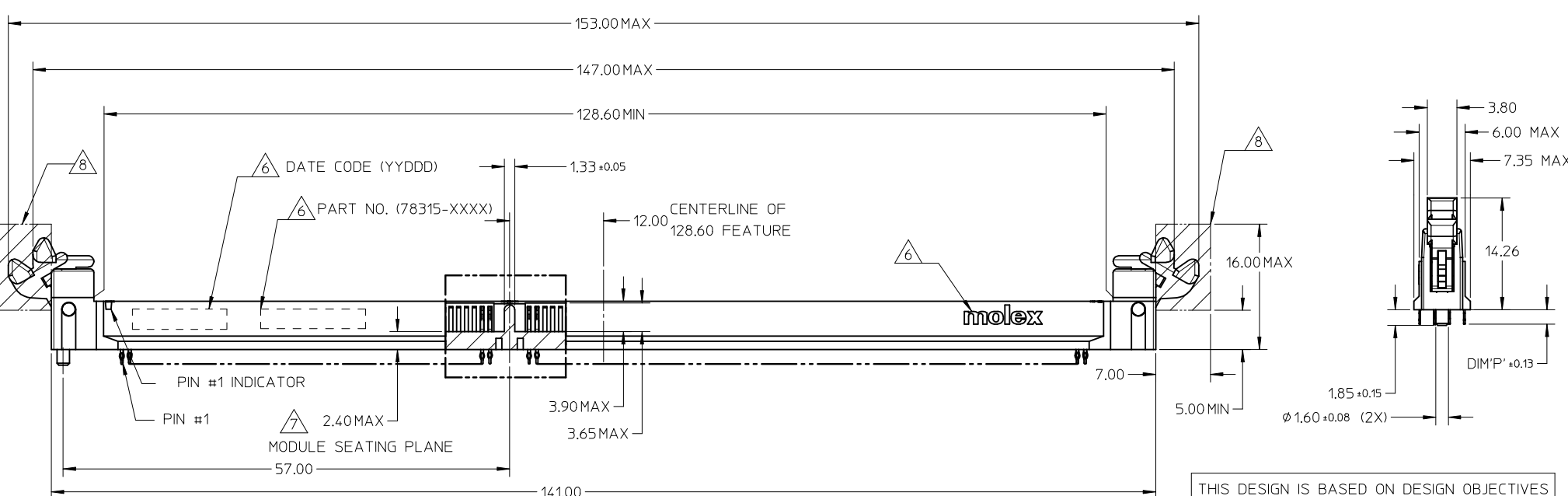
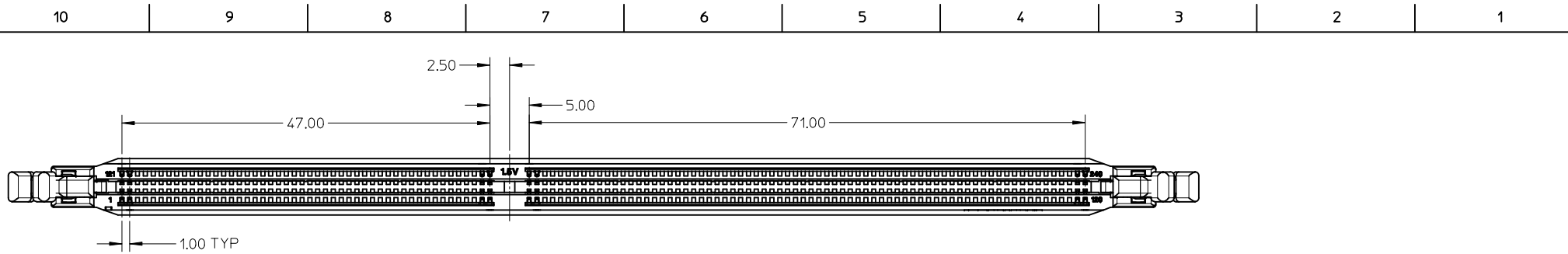
[78315Series](#)

Mates With

JEDEC standard 1.27mm modules

This document was generated on 05/17/2010

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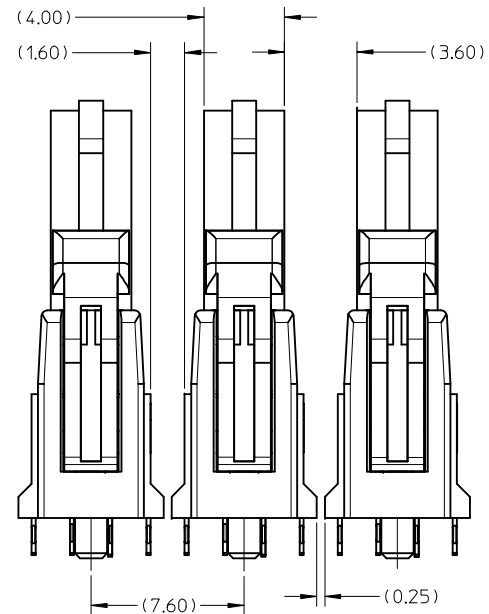
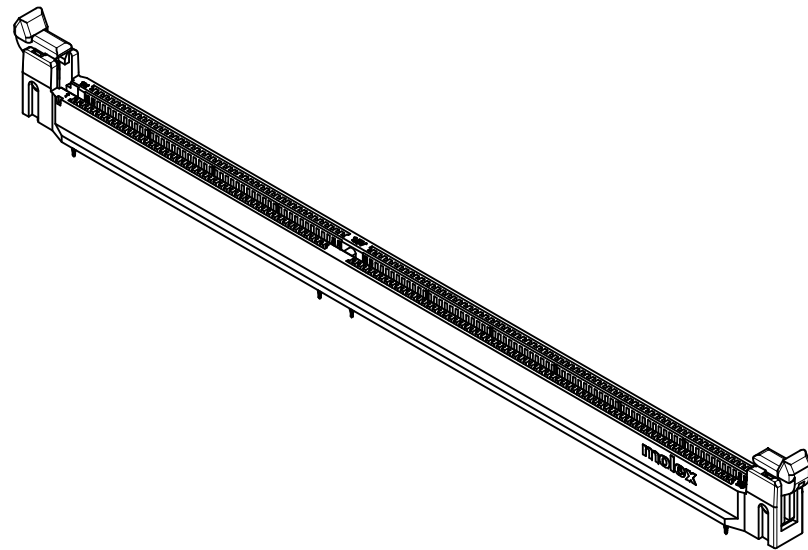
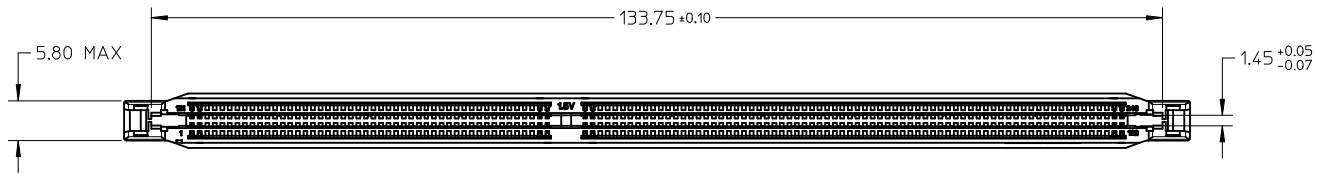


THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

NOTES:

- MATERIAL:
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
TERMINAL - COPPER ALLOY
 - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
 - PRODUCT SPECIFICATION: PS-78315-001
 - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
 - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
- △ 6 MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
 △ 7 MODULE SEATING PLANE FROM TOP OF PCB
 △ 8 KEEP OUT ZONE RESERVED FOR LATCH

ADDED OPTION EC NO: S2009-0332 DRW: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SILENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR	
		4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX MOLEX INCORPORATED	
		3 PLACES	± ---	± ---	APPROVED BY SILENI	DATE 2008/08/01		DOCUMENT NO. SD-78315-001
	2 PLACES	± 0.20	± ---	MATERIAL NO.		SEE TABLE		
	1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		ANGULAR ± 1 °		SIZE A3				

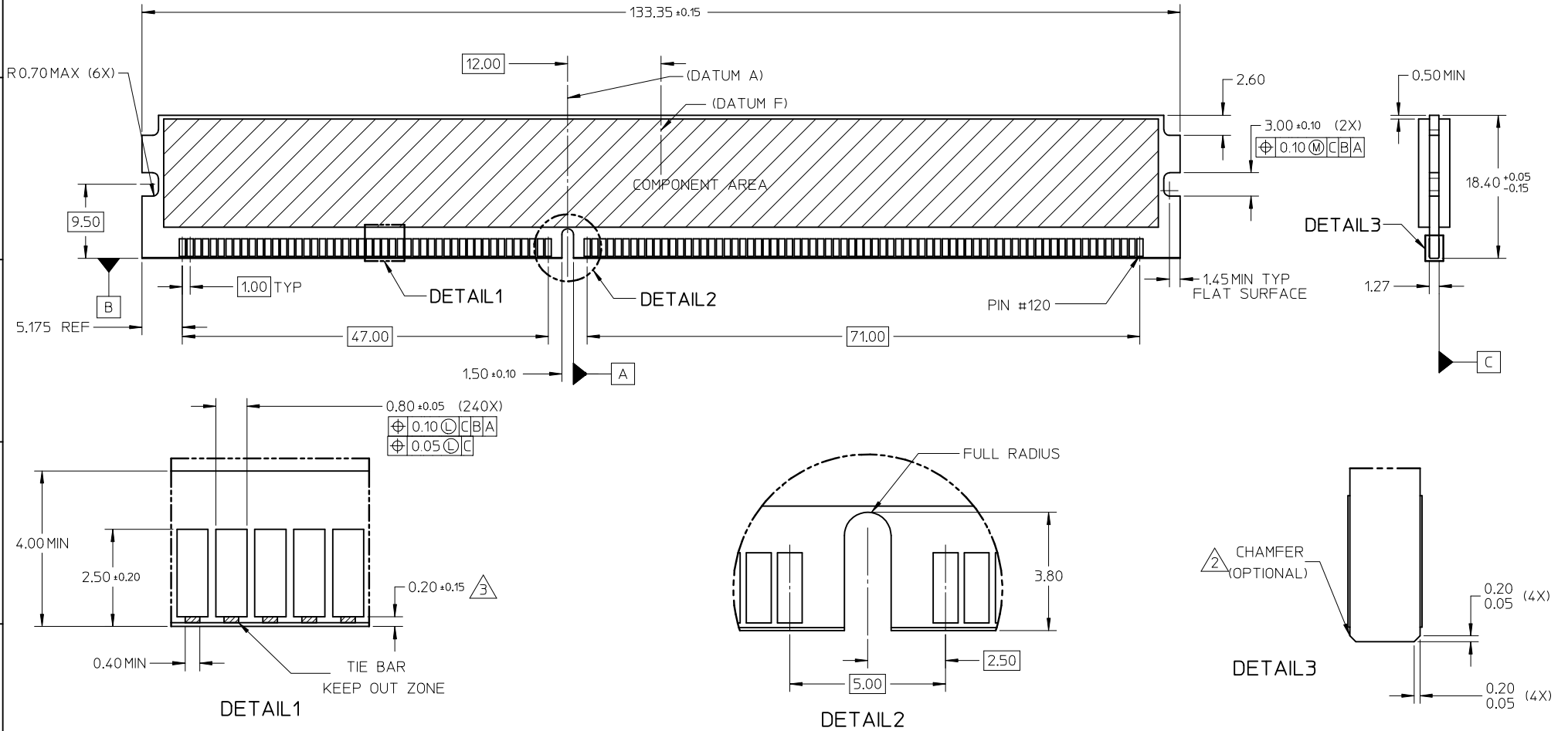


MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
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		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2008/08/01	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78315-001		2 OF 6	
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

009MODULE CARD
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)

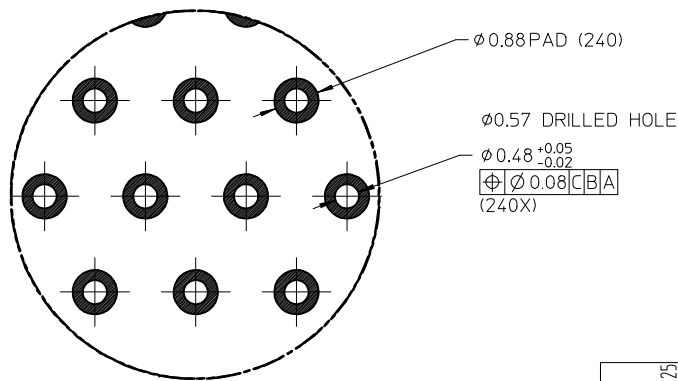
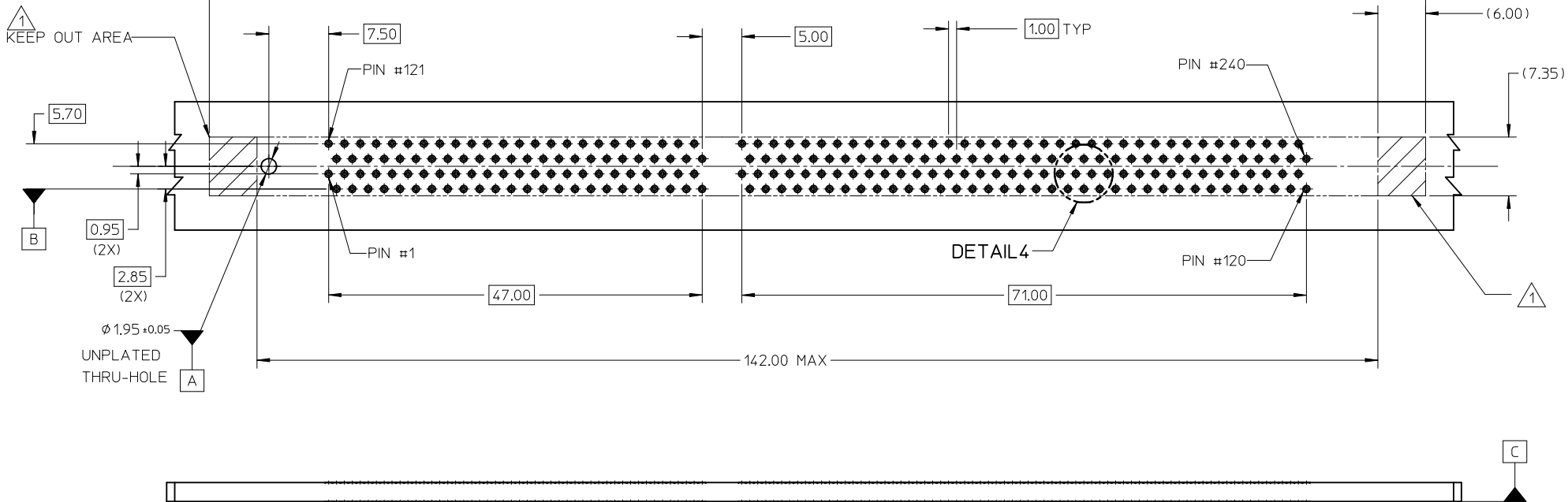


- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
 OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
 OVER 2.00 MICROMETERS NICKEL MUST
 USE AN ELECTRONIC CONTACT GRADE
 CORROSIVE BARRIER LUBRICANT
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		mm	INCH	DRAWN BY	DATE	TITLE				
		4 PLACES ± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)				
		3 PLACES ± ---	± ---	CCTEH	2008/07/30	1.00MM PITCH, 240 CKTS				
2 PLACES ± 0.20	± ---	SHLENI	2008/08/01	VERTICAL P/F, LOWLLCR						
1 PLACE ± ---	± ---	ANGULAR ± 1 °		APPROVED BY		DATE		MATERIAL NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					3 OF 6	

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



DETAIL 4

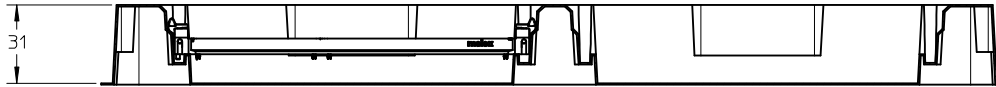
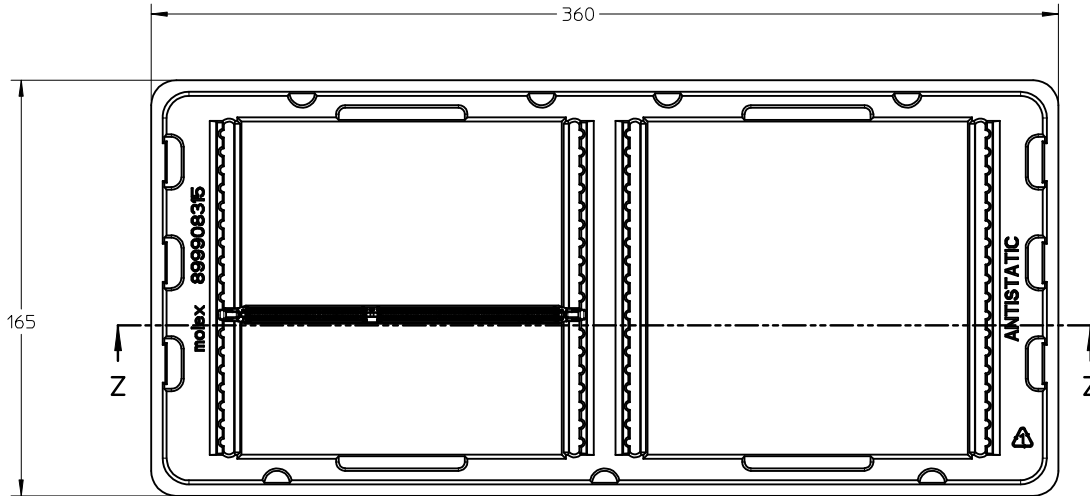
NOTES:

- 1. KEEP-OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS $\nabla=0$ $\square=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION																	
			<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>\pm ---</td> <td>\pm ---</td> </tr> <tr> <td>3 PLACES</td> <td>\pm ---</td> <td>\pm ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>\pm ---</td> </tr> <tr> <td>1 PLACE</td> <td>\pm ---</td> <td>\pm ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	\pm ---	\pm ---	3 PLACES	\pm ---	\pm ---	2 PLACES	± 0.20	\pm ---	1 PLACE	\pm ---	\pm ---	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
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1 PLACE	\pm ---	\pm ---																						
		ANGULAR $\pm 1^\circ$	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED																			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY SHLENI	DATE 2008/08/01	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78315-001	SHEET NO. 4 OF 6																	

9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

NOTE:

1. NO. OF CAVITY - 18 X 2 =36

ADDED OPTION EC NO: S2009-0332 U DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▼=0 □=0	mm	INCH	MM ONLY	NTS	METRIC		
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)	
	2 PLACES	± 0.20	± ---	CHECKED BY	DATE	1.00MM PITCH, 240 CKTS		
	1 PLACE	± ---	± ---	CCTEH	2008/07/30	VERTICAL P/F, LOWLLCR		
		ANGULAR ± 1 °		APPROVED BY	DATE	MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHLENI	2008/08/01	DOCUMENT NO.	SHEET NO.	
				MATERIAL NO.	SD-78315-001		5 OF 6	
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				A3				

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	
				CONTACT AREA	TAIL AREA
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0201				0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN/LEAD (BRIGHT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0011		2.85	2.60	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE

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			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR				
			ANGULAR ± 1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED				
					APPROVED BY SHLENI	DATE 2008/08/01	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78315-001	SHEET NO. 6 OF 6	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	